Lattice Semiconductor Corporation - LFXP15E-3FN484I Datasheet

Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	15000
Total RAM Bits	331776
Number of I/O	300
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	484-BBGA
Supplier Device Package	484-FPBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfxp15e-3fn484i

Introduction

The LatticeXP family of FPGA devices combine logic gates, embedded memory and high performance I/Os in a single architecture that is both non-volatile and infinitely reconfigurable to support cost-effective system designs.

The re-programmable non-volatile technology used in the LatticeXP family is the next generation ispXP™ technology. With this technology, expensive external configuration memories are not required and designs are secured from unauthorized read-back. In addition, instant-on capability allows for easy interfacing in many applications.

The ispLEVER® design tool from Lattice allows large complex designs to be efficiently implemented using the LatticeXP family of FPGA devices. Synthesis library support for LatticeXP is available for popular logic synthesis tools. The ispLEVER tool uses the synthesis tool output along with the constraints from its floor planning tools to place and route the design in the LatticeXP device. The ispLEVER tool extracts the timing from the routing and back-annotates it into the design for timing verification.

Lattice provides many pre-designed IP (Intellectual Property) ispLeverCORE™ modules for the LatticeXP family. By using these IPs as standardized blocks, designers are free to concentrate on the unique aspects of their design, increasing their productivity.

Figure 2-8. Per Quadrant Secondary Clock Selection

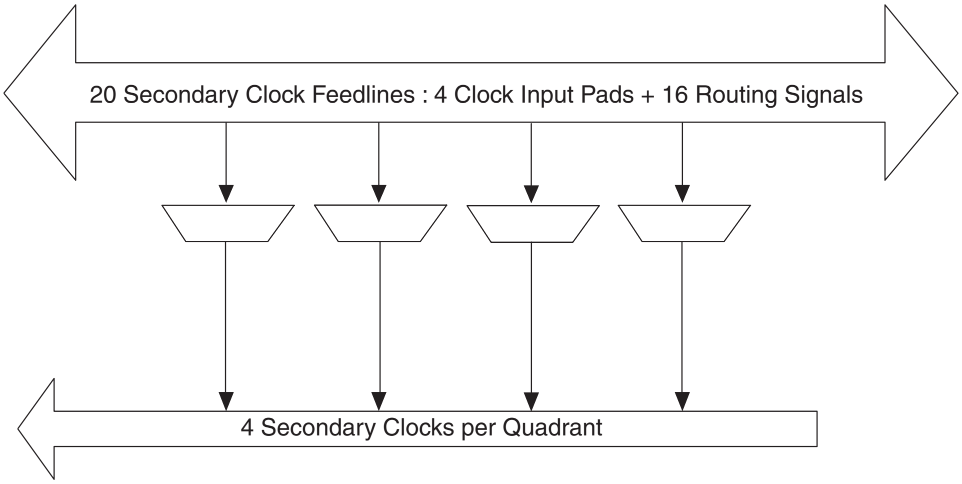
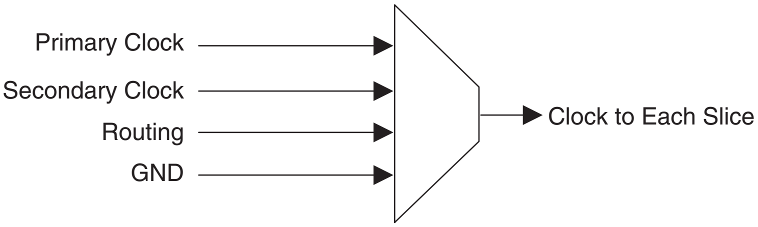


Figure 2-9. Slice Clock Selection



sysCLOCK Phase Locked Loops (PLLs)

The PLL clock input, from pin or routing, feeds into an input clock divider. There are three sources of feedback signals to the feedback divider: from CLKOP (PLL internal), from clock net (CLKOP or CLKOS) or from a user clock (PIN or logic). There is a PLL_LOCK signal to indicate that VCO has locked on to the input clock signal. Figure 2-10 shows the sysCLOCK PLL diagram.

The setup and hold times of the device can be improved by programming a delay in the feedback or input path of the PLL which will advance or delay the output clock with reference to the input clock. This delay can be either programmed during configuration or can be adjusted dynamically. In dynamic mode, the PLL may lose lock after adjustment and not relock until the t_{LOCK} parameter has been satisfied. Additionally, the phase and duty cycle block allows the user to adjust the phase and duty cycle of the CLKOS output.

The sysCLOCK PLLs provide the ability to synthesize clock frequencies. Each PLL has four dividers associated with it: input clock divider, feedback divider, post scalar divider and secondary clock divider. The input clock divider is used to divide the input clock signal, while the feedback divider is used to multiply the input clock signal. The post scalar divider allows the VCO to operate at higher frequencies than the clock output, thereby increasing the frequency range. The secondary divider is used to derive lower frequency outputs.

Figure 2-23. Output Register Block

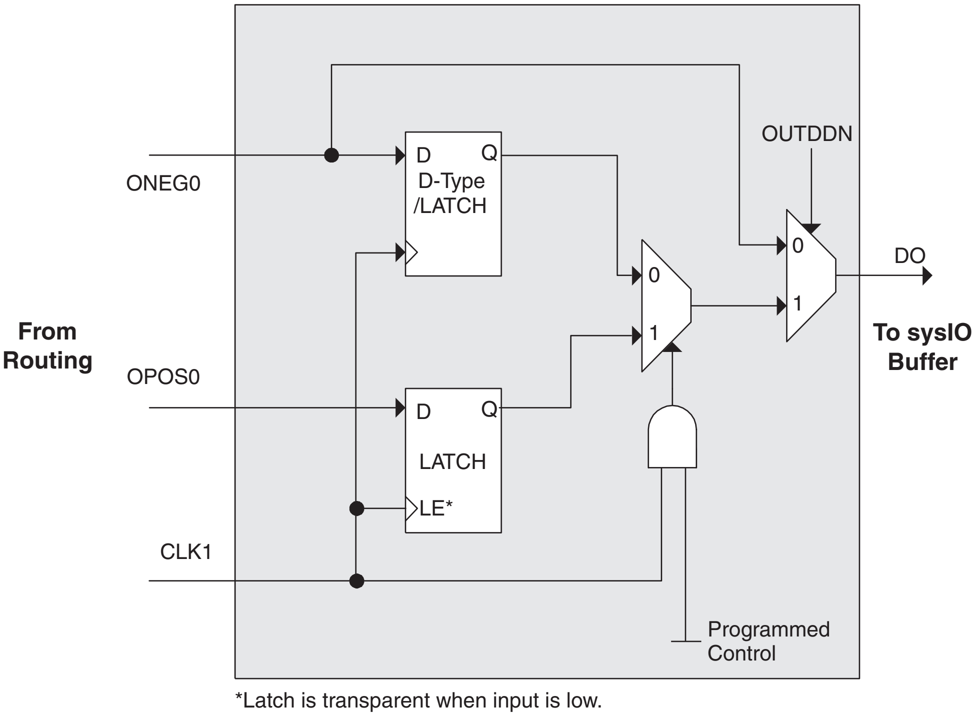
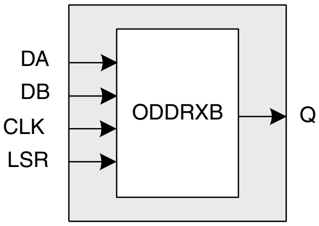


Figure 2-24. ODDRXB Primitive

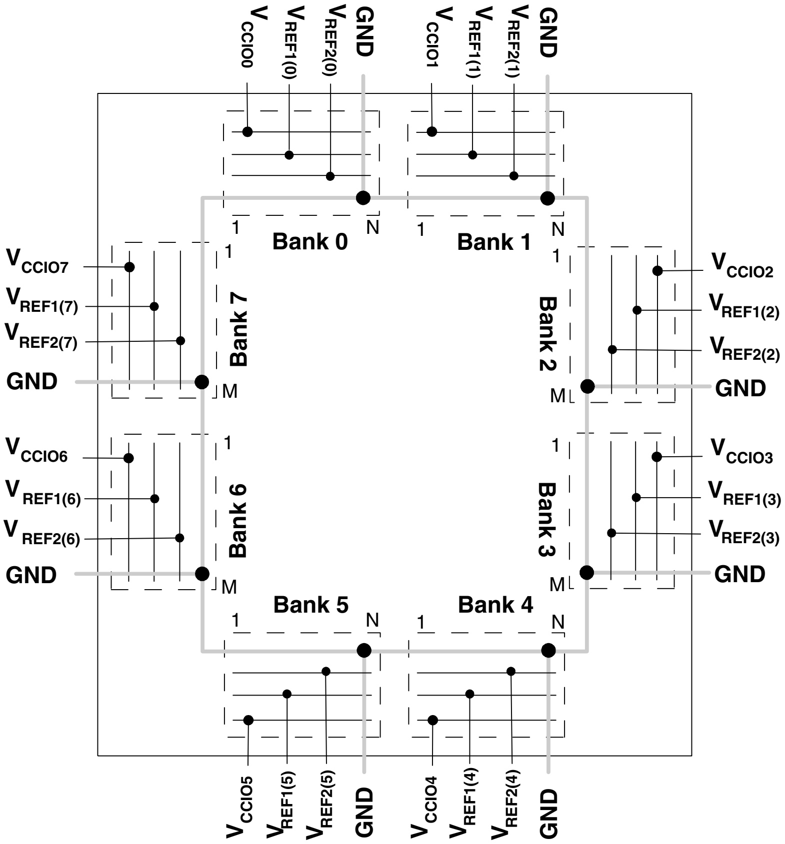


Tristate Register Block

The tristate register block provides the ability to register tri-state control signals from the core of the device before they are passed to the sysIO buffers. The block contains a register for SDR operation and an additional latch for DDR operation. Figure 2-25 shows the diagram of the Tristate Register Block.

In SDR mode, ONEG1 feeds one of the flip-flops that then feeds the output. The flip-flop can be configured a D-type or latch. In DDR mode, ONEG1 is fed into one register on the positive edge of the clock and OPOS1 is latched. A multiplexer running off the same clock selects the correct register for feeding to the output (D0).

Figure 2-28. LatticeXP Banks



Note: N and M are the maximum number of I/Os per bank.

LatticeXP devices contain two types of sysIO buffer pairs.

1. **Top and Bottom sysIO Buffer Pair (Single-Ended Outputs Only)**
   The sysIO buffer pairs in the top and bottom banks of the device consist of two single-ended output drivers and two sets of single-ended input buffers (both ratioed and referenced). The referenced input buffer can also be configured as a differential input.

   The two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential input buffer and the comp (complementary) pad is associated with the negative side of the differential input buffer.

   Only the I/Os on the top and bottom banks have PCI clamps. Note that the PCI clamp is enabled after $V_{CC,}$ V_{CCAUX} and V_{CCIO} are at valid operating levels and the device has been configured.

2. **Left and Right sysIO Buffer Pair (Differential and Single-Ended Outputs)**
   The sysIO buffer pairs in the left and right banks of the device consist of two single-ended output drivers, two sets of single-ended input buffers (both ratioed and referenced) and one differential output driver. The referenced input buffer can also be configured as a differential input. In these banks the two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential I/O, and the comp (complementary) pad is associated with the negative side of the differential I/O.

   Select I/Os in the left and right banks have LVDS differential output drivers. Refer to the Logic Signal Connections tables for more information.

Typical I/O Behavior During Power-up

The internal power-on-reset (POR) signal is deactivated when V_{CC} and V_{CCAUX} have reached satisfactory levels. After the POR signal is deactivated, the FPGA core logic becomes active. It is the user's responsibility to ensure that all other V_{CCIO} banks are active with valid input logic levels to properly control the output logic states of all the I/O banks that are critical to the application. The default configuration of the I/O pins in a blank device is tri-state with a weak pull-up to VCCIO. The I/O pins will not take on the user configuration until VCC, VCCAUX and VCCIO have reached satisfactory levels at which time the I/Os will take on the user-configured settings.

The V_{CC} and V_{CCAUX} supply the power to the FPGA core fabric, whereas the V_{CCIO} supplies power to the I/O buffers. In order to simplify system design while providing consistent and predictable I/O behavior, it is recommended that the I/O buffers be powered-up prior to the FPGA core fabric. V_{CCIO} supplies should be powered up before or together with the V_{CC} and V_{CCAUX} supplies.

Supported Standards

The LatticeXP sysIO buffer supports both single-ended and differential standards. Single-ended standards can be further subdivided into LVCMOS, LVTTL and other standards. The buffers support the LVTTL, LVCMOS 1.2, 1.5, 1.8, 2.5 and 3.3V standards. In the LVCMOS and LVTTL modes, the buffer has individually configurable options for drive strength, bus maintenance (weak pull-up, weak pull-down, or a bus-keeper latch) and open drain. Other single-ended standards supported include SSTL and HSTL. Differential standards supported include LVDS, BLVDS, LVPECL, differential SSTL and differential HSTL. Tables 2-7 and 2-8 show the I/O standards (together with their supply and reference voltages) supported by the LatticeXP devices. For further information on utilizing the sysIO buffer to support a variety of standards please see the details of additional technical documentation at the end of this data sheet.

Table 2-7. Supported Input Standards

Input Standard	V_{REF} (Nom.)	V_{CCIO}[1] (Nom.)
Single Ended Interfaces		
LVTTL	—	—
LVCMOS33[2]	—	—
LVCMOS25[2]	—	—
LVCMOS18	—	1.8
LVCMOS15	—	1.5
LVCMOS12[2]	—	—
PCI	—	3.3
HSTL18 Class I, II	0.9	—
HSTL18 Class III	1.08	—
HSTL15 Class I	0.75	—
HSTL15 Class III	0.9	—
SSTL3 Class I, II	1.5	—
SSTL2 Class I, II	1.25	—
SSTL18 Class I	0.9	—
Differential Interfaces		
Differential SSTL18 Class I	—	—
Differential SSTL2 Class I, II	—	—
Differential SSTL3 Class I, II	—	—
Differential HSTL15 Class I, III	—	—
Differential HSTL18 Class I, II, III	—	—
LVDS, LVPECL	—	—
BLVDS	—	—

1. When not specified V_{CCIO} can be set anywhere in the valid operating range.
2. JTAG inputs do not have a fixed threshold option and always follow $V_{CCJ.}$

sysIO Differential Electrical Characteristics

LVDS

Over Recommended Operating Conditions

Parameter Symbol	Parameter Description	Test Conditions	Min.	Typ.	Max.	Units
V_{INP}, V_{INM}	Input Voltage		0	—	2.4	V
V_{THD}	Differential Input Threshold		+/-100	—	—	mV
V_{CM}	Input Common Mode Voltage	100mV ≤ V_{THD}	$V_{THD}/2$	1.2	1.8	V
		200mV ≤ V_{THD}	$V_{THD}/2$	1.2	1.9	V
		350mV ≤ V_{THD}	$V_{THD}/2$	1.2	2.0	V
I_{IN}	Input current	Power on or power off	—	—	+/-10	µA
V_{OH}	Output high voltage for V_{OP} or V_{OM}	R_T = 100 ohms	—	1.38	1.60	V
V_{OL}	Output low voltage for V_{OP} or V_{OM}	R_T = 100 ohms	0.9V	1.03	—	V
V_{OD}	Output voltage differential	(V_{OP} - V_{OM}), R_T = 100 ohms	250	350	450	mV
ΔV_{OD}	Change in V_{OD} between high and low		—	—	50	mV
V_{OS}	Output voltage offset	(V_{OP} - V_{OM})/2, R_T = 100 ohms	1.125	1.25	1.375	V
ΔV_{OS}	Change in V_{OS} between H and L		—	—	50	mV
I_{OSD}	Output short circuit current	V_{OD} = 0V Driver outputs shorted	—	—	6	mA

Figure 3-4. RSDS (Reduced Swing Differential Standard)

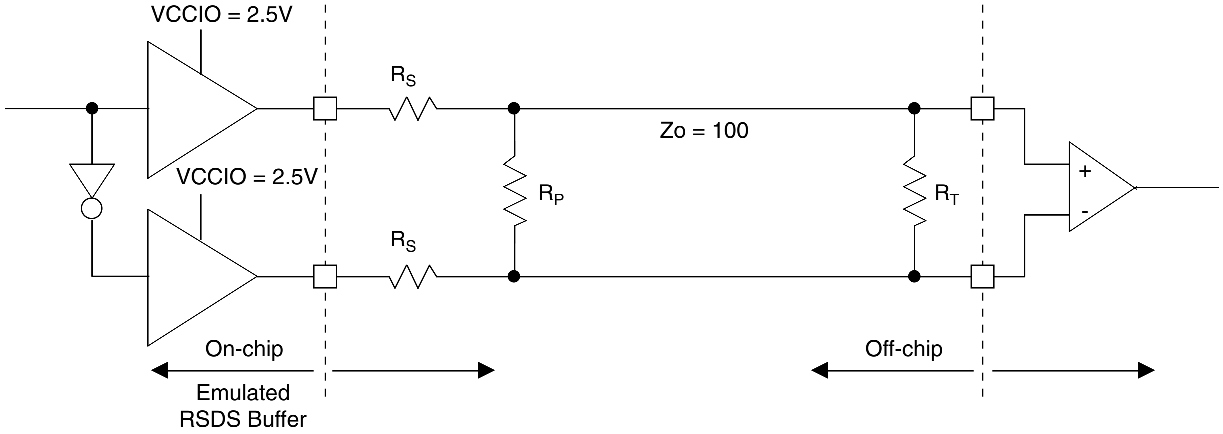


Table 3-4. RSDS DC Conditions

Parameter	Description	Typical	Units
Z_{OUT}	Output impedance	20	ohms
R_S	Driver series resistor	300	ohms
R_P	Driver parallel resistor	121	ohms
R_T	Receiver termination	100	ohms
V_{OH}	Output high voltage	1.35	V
V_{OL}	Output low voltage	1.15	V
V_{OD}	Output differential voltage	0.20	V
V_{CM}	Output common mode voltage	1.25	V
Z_{BACK}	Back impedance	101.5	ohms
I_{DC}	DC output current	3.66	mA

Typical Building Block Function Performance[1]

Pin-to-Pin Performance (LVCMOS25 12 mA Drive)

Function	-5 Timing	Units
Basic Functions		
16-bit decoder	6.1	ns
32-bit decoder	7.3	ns
64-bit decoder	8.2	ns
4:1 MUX	4.9	ns
8:1 MUX	5.3	ns
16:1 MUX	5.7	ns
32:1 MUX	6.3	ns

Register to Register Performance

Function	-5 Timing	Units
Basic Functions		
16-bit decoder	351	MHz
32-bit decoder	248	MHz
64-bit decoder	237	MHz
4:1 MUX	590	MHz
8:1 MUX	523	MHz
16:1 MUX	434	MHz
32:1 MUX	355	MHz
8-bit adder	343	MHz
16-bit adder	292	MHz
64-bit adder	130	MHz
16-bit counter	388	MHz
32-bit counter	295	MHz
64-bit counter	200	MHz
64-bit accumulator	164	MHz
Embedded Memory Functions		
Single Port RAM 256x36 bits	254	MHz
True-Dual Port RAM 512x18 bits	254	MHz
Distributed Memory Functions		
16x2 SP RAM	434	MHz
64x2 SP RAM	332	MHz
128x4 SP RAM	235	MHz
32x2 PDP RAM	322	MHz
64x4 PDP RAM	291	MHz

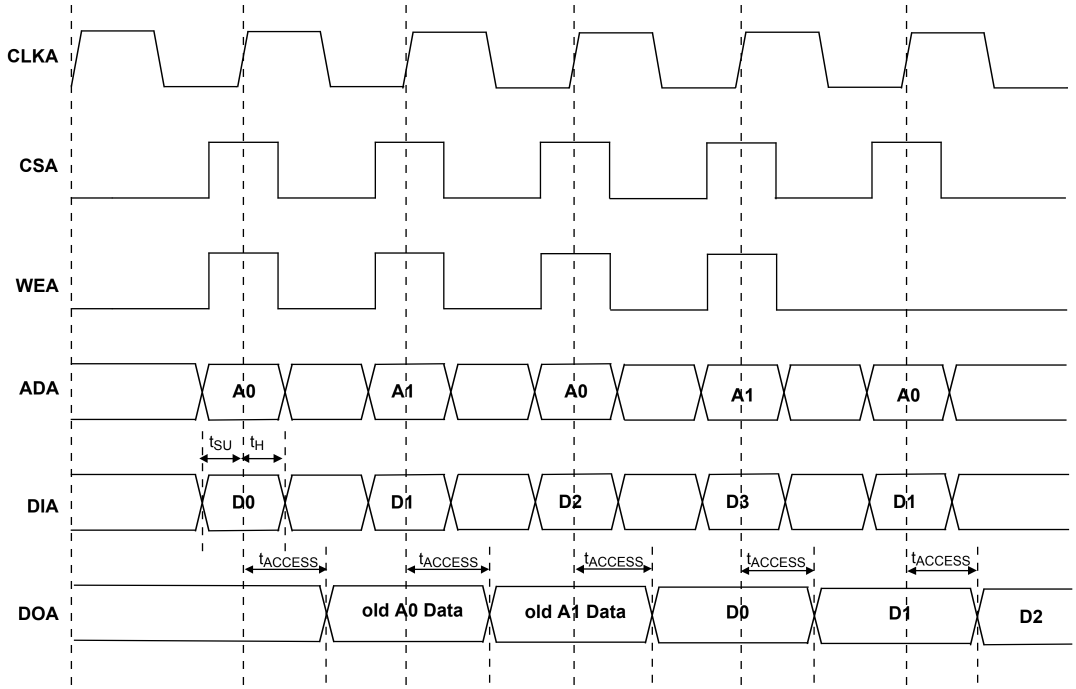
1. These timing numbers were generated using the ispLEVER design tool. Exact performance may vary with design and tool version. The tool uses internal parameters that have been characterized but are not tested on every device.

Timing v.F0.11

Derating Logic Timing

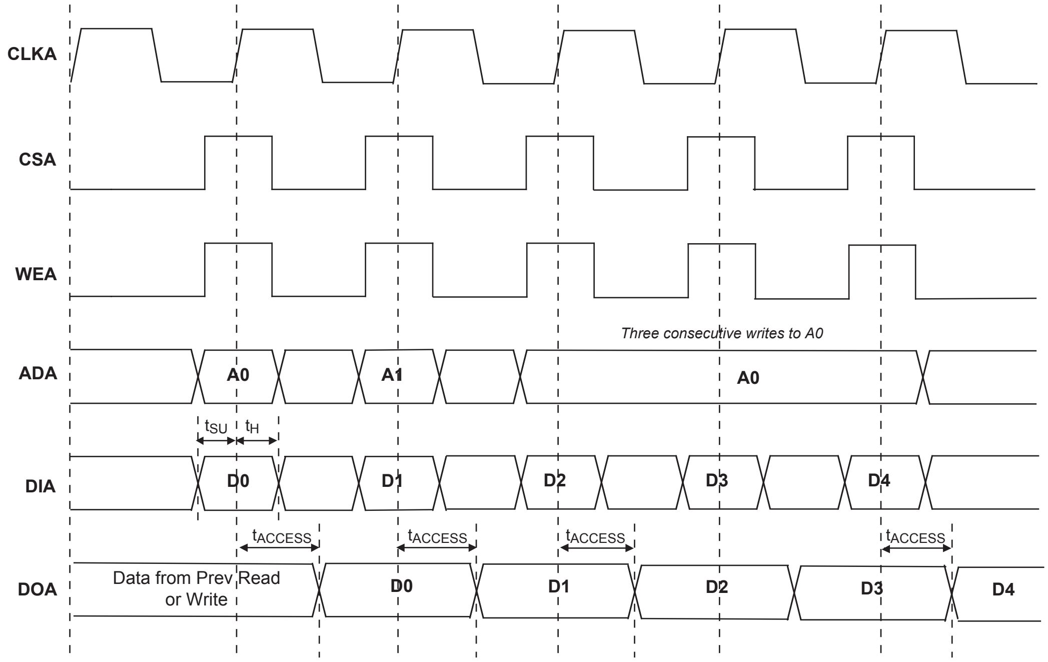
Logic timing provided in the following sections of this data sheet and in the ispLEVER design tools are worst case numbers in the operating range. Actual delays at nominal temperature and voltage for best-case process can be much better than the values given in the tables. The ispLEVER design tool from Lattice can provide logic timing numbers at a particular temperature and voltage.

Figure 3-10. Read Before Write (SP Read/Write on Port A, Input Registers Only)



Note: Input data and address are registered at the positive edge of the clock and output data appears after the positive of the clock.

Figure 3-11. Write Through (SP Read/Write On Port A, Input Registers Only)



Note: Input data and address are registered at the positive edge of the clock and output data appears after the positive of the clock.

LatticeXP Family Timing Adders[1] (Continued)

Over Recommended Operating Conditions

Buffer Type	Description	-5	-4	-3	Units
HSTL15_I	HSTL_15 class I	0.2	0.2	0.2	ns
HSTL15_III	HSTL_15 class III	0.2	0.2	0.2	ns
HSTL15D_I	Differential HSTL 15 class I	0.2	0.2	0.2	ns
HSTL15D_III	Differential HSTL 15 class III	0.2	0.2	0.2	ns
SSTL33_I	SSTL_3 class I	0.1	0.1	0.1	ns
SSTL33_II	SSTL_3 class II	0.3	0.3	0.3	ns
SSTL33D_I	Differential SSTL_3 class I	0.1	0.1	0.1	ns
SSTL33D_II	Differential SSTL_3 class II	0.3	0.3	0.3	ns
SSTL25_I	SSTL_2 class I	-0.1	-0.1	-0.1	ns
SSTL25_II	SSTL_2 class II	0.3	0.3	0.3	ns
SSTL25D_I	Differential SSTL_2 class I	-0.1	-0.1	-0.1	ns
SSTL25D_II	Differential SSTL_2 class II	0.3	0.3	0.3	ns
SSTL18_I	SSTL_1.8 class I	0.1	0.1	0.1	ns
SSTL18D_I	Differential SSTL_1.8 class I	0.1	0.1	0.1	ns
LVTTL33_4mA	LVTTL 4mA drive	0.8	0.8	0.8	ns
LVTTL33_8mA	LVTTL 8mA drive	0.5	0.5	0.5	ns
LVTTL33_12mA	LVTTL 12mA drive	0.3	0.3	0.3	ns
LVTTL33_16mA	LVTTL 16mA drive	0.4	0.4	0.4	ns
LVTTL33_20mA	LVTTL 20mA drive	0.3	0.3	0.3	ns
LVCMOS33_2mA	LVCMOS 3.3 2mA drive	0.8	0.8	0.8	ns
LVCMOS33_4mA	LVCMOS 3.3 4mA drive	0.8	0.8	0.8	ns
LVCMOS33_8mA	LVCMOS 3.3 8mA drive	0.5	0.5	0.5	ns
LVCMOS33_12mA	LVCMOS 3.3 12mA drive	0.3	0.3	0.3	ns
LVCMOS33_16mA	LVCMOS 3.3 16mA drive	0.4	0.4	0.4	ns
LVCMOS33_20mA	LVCMOS 3.3 20mA drive	0.3	0.3	0.3	ns
LVCMOS25_2mA	LVCMOS 2.5 2mA drive	0.7	0.7	0.7	ns
LVCMOS25_4mA	LVCMOS 2.5 4mA drive	0.7	0.7	0.7	ns
LVCMOS25_8mA	LVCMOS 2.5 8mA drive	0.4	0.4	0.4	ns
LVCMOS25_12mA	LVCMOS 2.5 12mA drive	0.0	0.0	0.0	ns
LVCMOS25_16mA	LVCMOS 2.5 16mA drive	0.2	0.2	0.2	ns
LVCMOS25_20mA	LVCMOS 2.5 20mA drive	0.4	0.4	0.4	ns
LVCMOS18_2mA	LVCMOS 1.8 2mA drive	0.6	0.6	0.6	ns
LVCMOS18_4mA	LVCMOS 1.8 4mA drive	0.6	0.6	0.6	ns
LVCMOS18_8mA	LVCMOS 1.8 8mA drive	0.4	0.4	0.4	ns
LVCMOS18_12mA	LVCMOS 1.8 12mA drive	0.2	0.2	0.2	ns
LVCMOS18_16mA	LVCMOS 1.8 16mA drive	0.2	0.2	0.2	ns
LVCMOS15_2mA	LVCMOS 1.5 2mA drive	0.6	0.6	0.6	ns
LVCMOS15_4mA	LVCMOS 1.5 4mA drive	0.6	0.6	0.6	ns
LVCMOS15_8mA	LVCMOS 1.5 8mA drive	0.2	0.2	0.2	ns
LVCMOS12_2mA	LVCMOS 1.2 2mA drive	0.4	0.4	0.4	ns
LVCMOS12_6mA	LVCMOS 1.2 6mA drive	0.4	0.4	0.4	ns
PCI33	PCI33	0.3	0.3	0.3	ns

1. General timing numbers based on LVCMOS 2.5, 12mA.

Timing v.F0.11

LatticeXP Family Data Sheet
Pinout Information

November 2007 Data Sheet DS1001

Signal Descriptions

Signal Name	I/O	Descriptions
General Purpose		
P[Edge] [Row/Column Number*]_[A/B]	I/O	[Edge] indicates the edge of the device on which the pad is located. Valid edge designations are L (Left), B (Bottom), R (Right), T (Top). [Row/Column Number] indicates the PFU row or the column of the device on which the PIC exists. When Edge is T (Top) or (Bottom), only need to specify Row Number. When Edge is L (Left) or R (Right), only need to specify Column Number. [A/B] indicates the PIO within the PIC to which the pad is connected. Some of these user programmable pins are shared with special function pins. These pin when not used as special purpose pins can be programmed as I/Os for user logic. During configuration, the user-programmable I/Os are tri-stated with an internal pull-up resistor enabled. If any pin is not used (or not bonded to a package pin), it is also tri-stated with an internal pull-up resistor enabled after configuration.
GSRN	I	Global RESET signal. (Active low). Any I/O pin can be configured to be GSRN.
NC	—	No connect.
GND	—	GND - Ground. Dedicated Pins.
V_{CC}	—	VCC - The power supply pins for core logic. Dedicated Pins.
V_{CCAUX}	—	V_{CCAUX} - The Auxiliary power supply pin. It powers all the differential and referenced input buffers. Dedicated Pins.
V_{CCP0}	—	Voltage supply pins for ULM0PLL (and LLM1PLL[1]).
V_{CCP1}	—	Voltage supply pins for URM0PLL (and LRM1PLL[1]).
GNDP0	—	Ground pins for ULM0PLL (and LLM1PLL[1]).
GNDP1	—	Ground pins for URM0PLL (and LRM1PLL[1]).
V_{CCIOx}	—	V_{CCIO} - The power supply pins for I/O bank x. Dedicated Pins.
$V_{REF1(x)}$, $V_{REF2(x)}$	—	Reference supply pins for I/O bank x. Pre-determined pins in each bank are assigned as V_{REF} inputs. When not used, they may be used as I/O pins.
PLL and Clock Functions (Used as user programmable I/O pins when not in use for PLL or clock pins)		
[LOC][num]_PLL[T, C]_IN_A	—	Reference clock (PLL) input Pads: ULM, LLM, URM, LRM, num = row from center, T = true and C = complement, index A, B, C...at each side.
[LOC][num]_PLL[T, C]_FB_A	—	Optional feedback (PLL) input Pads: ULM, LLM, URM, LRM, num = row from center, T = true and C = complement, index A, B, C...at each side.
PCLK[T, C]_[n:0]_[3:0]	—	Primary Clock Pads, T = true and C = complement, n per side, indexed by bank and 0,1, 2, 3 within bank.
[LOC]DQS[num]	—	DQS input Pads: T (Top), R (Right), B (Bottom), L (Left), DQS, num = Ball function number. Any pad can be configured to be DQS output.

Power Supply and NC Connections

Signals	100 TQFP	144 TQFP	208 PQFP	256 fpBGA	388 fpBGA	484 fpBGA
V_{CC}	28, 77	14, 39, 73, 112	19, 35, 53, 80, 107, 151, 158, 182	D4, D13, E5, E12, M5, M12, N4, N13	H9, J8, J15, K8, K15, L8, L15, M8, M15, N8, N15, P8, P15, R9	F10, F13, G9, G10, G13, G14, H8, H15, J7, J16, K6, K7, K16, K17, N6, N7, N16, N17, P7, P16, R8, R15, T9, T10, T13, T14, U10, U13
V_{CCIO0}	94	133	189, 199	F7, F8	G8, G9, G10, G11, H8	F11, G11, H10, H11
V_{CCIO1}	82	119	167, 177	F9, F10	G12, G13, G14, G15, H15	F12, G12, H12, H13
V_{CCIO2}	65	98	140, 149	G11, H11	H16, J16, K16, L16	K15, L15, L16, L17
V_{CCIO3}	58	88	115, 125	J11, K11	M16, N16, P16, R16	M15, M16, M17, N15
V_{CCIO4}	47	61, 68	87, 97	L9, L10	R15, T12, T13, T14, T15	R12, R13, T12, U12
V_{CCIO5}	38	49	64, 74	L7, L8	R8, T8, T9, T10, T11	R10, R11, T11, U11
V_{CCIO6}	22	21	28, 41	J6, K6	M7, N7, P7, R7	M6, M7, M8, N8
V_{CCIO7}	7	8	13, 23	G6, H6	H7, J7, K7, L7	K8, L6, L7, L8
V_{CCJ}	73	108	154	D16	E20	E20
V_{CCP0}	17	19	25	H4	M2	L5
V_{CCP1}	60	91	128	J12	M21	L18
V_{CCAUX}	25, 71	36, 106	50, 152	E4, E13, M4, M13	G7, G16, T7, T16	G7, G8, G15, G16, H7, H16, R7, R16, T7, T8, T15, T16
GND[1]	10, 18, 21, 33, 43, 44, 52, 59, 68, 84, 90, 99	3, 11, 20, 28, 44, 54, 56, 64, 75, 85, 90, 101, 121, 127, 136	5, 7, 16, 26, 38, 47, 49, 59, 69, 79, 82, 92, 106, 109, 118, 121, 127, 130, 135, 143, 163, 172, 181, 184, 194, 207	A1, A16, F6, F11, G7, G8, G9, G10, H5, H7, H8, H9, H10, J7, J8, J9, J10, J13, K7, K8, K9, K10, L6, L11, T1, T16	A1, A22, H10, H11, H12, H13, H14, J9, J10, J11, J12, J13, J14, K9, K10, K11, K12, K13, K14, L9, L10, L11, L12, L13, L14, M9, M10, M11, M12, M13, M14, N1, N9, N10, N11, N12, N13, N14, N22, P9, P10, P11, P12, P13, P14, R10, R11, R12, R13, R14, AB1, AB22	A1, A2, A21, A22, B1, B22, H9, H14, J8, J9, J10, J11, J12, J13, J14, J15, K9, K10, K11, K12, K13, K14, L9, L10, L11, L12, L13, L14, M9, M10, M11, M12, M13, M14, M20, N2, N9, N10, N11, N12, N13, N14, P8, P9, P10, P11, P12, P13, P14, P15, R9, R14, AA1, AA22, AB1, AB2, AB21, AB22
NC[2]	—	—	XP3: 27, 33, 34, 129, 133, 134	—	XP10: C2, C15, C16, C17, D4, D5, D6, D7, D16, D17, E4, E19, W3, W4, W7, W17, W18, W19, W20, Y3, Y15, Y16, AA1, AA2	XP15: B21, C4, C5, C6, C18, C19, C20, C21, D6, D18, E4, E6, E18, F6, L1, L19, L20, M1, M2, M19, M21, N1, N21, N22, P1, P2, U5, U6, U17, U18, V5, V6, V17, V18, W17, W18, W19, Y3, Y4, Y5

1. All grounds must be electrically connected at the board level.
2. NC pins should not be connected to any active signals, V_{CC} or GND.

LFXP3 & LFXP6 Logic Signal Connections: 144 TQFP (Cont.)

Pin Number	LFXP3				LFXP6			
	Pin Function	Bank	Differential	Dual Function	Pin Function	Bank	Differential	Dual Function
139	PT6A	0	-	DI	PT9A	0	-	DI
140	PT5A	0	-	CSN	PT8A	0	-	CSN
141	PT3B	0	-	VREF2_0	PT6B	0	-	VREF2_0
142	CFG0	0	-	-	CFG0	0	-	-
143	CFG1	0	-	-	CFG1	0	-	-
144	DONE	0	-	-	DONE	0	-	-

1. Applies to LFXP “C” only.
2. Applies to LFXP “E” only.
3. Supports dedicated LVDS outputs.

LFXP6 & LFXP10 Logic Signal Connections: 256 fpBGA (Cont.)

	LFXP6				LFXP10			
Ball Number	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
R8	PB16A	5	T	-	PB20A	5	T	-
T9	PB16B	5	C	-	PB20B	5	C	-
R9	PB17A	4	T	-	PB21A	4	T	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
P9	PB17B	4	C	-	PB21B	4	C	-
T10	PB18A	4	T	PCLKT4_0	PB22A	4	T	PCLKT4_0
T11	PB18B	4	C	PCLKC4_0	PB22B	4	C	PCLKC4_0
R10	PB19A	4	T	-	PB23A	4	T	-
P10	PB19B	4	C	-	PB23B	4	C	-
N9	PB20A	4	-	-	PB24A	4	-	-
M9	PB21B	4	-	-	PB25B	4	-	-
R12	PB22A	4	T	DQS	PB26A	4	T	DQS
-	GNDIO4	4	-	-	GNDIO4	4	-	-
T12	PB22B	4	C	VREF1_4	PB26B	4	C	VREF1_4
P13	PB23A	4	T	-	PB27A	4	T	-
R13	PB23B	4	C	-	PB27B	4	C	-
M11	PB24A	4	T	-	PB28A	4	T	-
N11	PB24B	4	C	-	PB28B	4	C	-
N10	PB25A	4	T	-	PB29A	4	T	-
M10	PB25B	4	C	-	PB29B	4	C	-
T13	PB26A	4	T	-	PB30A	4	T	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
P14	PB26B	4	C	-	PB30B	4	C	-
R11	PB27A	4	T	VREF2_4	PB31A	4	T	VREF2_4
P12	PB27B	4	C	-	PB31B	4	C	-
T14	PB28A	4	-	-	PB32A	4	-	-
R14	PB29B	4	-	-	PB33B	4	-	-
P11	PB30A	4	T	DQS	PB34A	4	T	DQS
N12	PB30B	4	C	-	PB34B	4	C	-
T15	PB31A	4	T	-	PB35A	4	T	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
R15	PB31B	4	C	-	PB35B	4	C	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-
P15	PR26B	3	C[3]	-	PR34B	3	C	RLM0_PLLC_FB_A
N15	PR26A	3	T[3]	-	PR34A	3	T	RLM0_PLLT_FB_A
P16	PR24B	3	C[3]	-	PR33B	3	C[3]	-
R16	PR24A	3	T[3]	DQS	PR33A	3	T[3]	DQS
M15	PR15B	3	-	-	PR32B	3	-	-
N14	PR23B	3	-	VREF1_3	PR31A	3	-	VREF1_3
-	GNDIO3	3	-	-	GNDIO3	3	-	-
M14	PR25B	3	C	-	PR29B	3	C	-
L13	PR25A	3	T	-	PR29A	3	T	-

LFXP10, LFXP15 & LFXP20 Logic Signal Connections: 388 fpBGA

	LFXP10				LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function
F4	PROGRAMN	7	-	-	PROGRAMN	7	-	-	PROGRAMN	7	-	-
G4	CCLK	7	-	-	CCLK	7	-	-	CCLK	7	-	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-	GNDIO7	7	-	-
D2	PL2A	7	T[3]	-	PL6A	7	T[3]	-	PL6A	7	T[3]	-
D1	PL2B	7	C[3]	-	PL6B	7	C[3]	-	PL6B	7	C[3]	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-	GNDIO7	7	-	-
E2	PL3A	7	T	LUM0_PLLT_FB_A	PL7A	7	T	LUM0_PLLT_FB_A	PL7A	7	T	LUM0_PLLT_FB_A
E3	PL3B	7	C	LUM0_PLLC_FB_A	PL7B	7	C	LUM0_PLLC_FB_A	PL7B	7	C	LUM0_PLLC_FB_A
F3	PL4A	7	T[3]	-	PL8A	7	T[3]	-	PL8A	7	T[3]	-
F2	PL4B	7	C[3]	-	PL8B	7	C[3]	-	PL8B	7	C[3]	-
H4	PL5A	7	-	-	PL9A	7	-	-	PL9A	7	-	-
H3	PL6B	7	-	VREF1_7	PL10B	7	-	VREF1_7	PL10B	7	-	VREF1_7
G3	PL7A	7	T[3]	DQS	PL11A	7	T[3]	DQS	PL11A	7	T[3]	DQS
G2	PL7B	7	C[3]	-	PL11B	7	C[3]	-	PL11B	7	C[3]	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-	GNDIO7	7	-	-
F1	PL8A	7	T	-	PL12A	7	T	-	PL12A	7	T	-
E1	PL8B	7	C	-	PL12B	7	C	-	PL12B	7	C	-
J4	PL9A	7	T[3]	-	PL13A	7	T[3]	-	PL13A	7	T[3]	-
K4	PL9B	7	C[3]	-	PL13B	7	C[3]	-	PL13B	7	C[3]	-
G1	PL11A	7	T[3]	-	PL15A	7	T[3]	-	PL15A	7	T[3]	-
H2	PL11B	7	C[3]	-	PL15B	7	C[3]	-	PL15B	7	C[3]	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-	GNDIO7	7	-	-
J2	PL12A	7	T	LUM0_PLLT_IN_A	PL16A	7	T	LUM0_PLLT_IN_A	PL16A	7	T	LUM0_PLLT_IN_A
H1	PL12B	7	C	LUM0_PLLC_IN_A	PL16B	7	C	LUM0_PLLC_IN_A	PL16B	7	C	LUM0_PLLC_IN_A
J1	PL13A	7	T[3]	-	PL17A	7	T[3]	-	PL17A	7	T[3]	-
K2	PL13B	7	C[3]	-	PL17B	7	C[3]	-	PL17B	7	C[3]	-
K3	PL14A	7	-	VREF2_7	PL18A	7	-	VREF2_7	PL18A	7	-	VREF2_7
J3	PL15B	7	-	-	PL19B	7	-	-	PL19B	7	-	-
K1	PL16A	7	T[3]	DQS	PL20A	7	T[3]	DQS	PL20A	7	T[3]	DQS
-	GNDIO7	7	-	-	GNDIO7	7	-	-	GNDIO7	7	-	-
L2	PL16B	7	C[3]	-	PL20B	7	C[3]	-	PL20B	7	C[3]	-
L3	PL17A	7	T	-	PL21A	7	T	-	PL21A	7	T	-
L4	PL17B	7	C	-	PL21B	7	C	-	PL21B	7	C	-
L1	PL18A	7	T[3]	-	PL22A	7	T[3]	-	PL22A	7	T[3]	-
M1	PL18B	7	C[3]	-	PL22B	7	C[3]	-	PL22B	7	C[3]	-
M2	VCCP0	-	-	-	VCCP0	-	-	-	VCCP0	-	-	-
N1	GNDP0	-	-	-	GNDP0	-	-	-	GNDP0	-	-	-
M3	PL19A	6	T[3]	-	PL23A	6	T[3]	-	PL27A	6	T[3]	-
M4	PL19B	6	C[3]	-	PL23B	6	C[3]	-	PL27B	6	C[3]	-
P1	PL20A	6	T	PCLKT6_0	PL24A	6	T	PCLKT6_0	PL28A	6	T	PCLKT6_0
-	GNDIO6	6	-	-	GNDIO6	6	-	-	GNDIO6	6	-	-
N2	PL20B	6	C	PCLKC6_0	PL24B	6	C	PCLKC6_0	PL28B	6	C	PCLKC6_0
R1	PL21A	6	T[3]	-	PL25A	6	T[3]	-	PL29A	6	T[3]	-
P2	PL21B	6	C[3]	-	PL25B	6	C[3]	-	PL29B	6	C[3]	-
N3	PL22A	6	-	-	PL26A	6	-	-	PL30A	6	-	-
N4	PL23B	6	-	VREF1_6	PL27B	6	-	VREF1_6	PL31B	6	-	VREF1_6
T1	PL24A	6	T[3]	DQS	PL28A	6	T[3]	DQS	PL32A	6	T[3]	DQS
R2	PL24B	6	C[3]	-	PL28B	6	C[3]	-	PL32B	6	C[3]	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-	GNDIO6	6	-	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

	LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
B3	PT8B	0	C	-	PT12B	0	C	-
A3	PT8A	0	T	-	PT12A	0	T	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-
D7	PT7B	0	C	-	PT11B	0	C	-
C7	PT7A	0	T	DQS	PT11A	0	T	DQS
B2	PT6B	0	-	-	PT10B	0	-	-
C2	PT5A	0	-	-	PT9A	0	-	-
C3	PT4B	0	C	-	PT8B	0	C	-
D3	PT4A	0	T	-	PT8A	0	T	-
F7	PT3B	0	C	-	PT7B	0	C	-
E7	PT3A	0	T	-	PT7A	0	T	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-
C6	-	-	-	-	PT6B	0	C	-
D6	-	-	-	-	PT6A	0	T	-
C5	-	-	-	-	PT5B	0	C	-
C4	-	-	-	-	PT5A	0	T	-
F6	-	-	-	-	PT4B	0	C	-
E6	-	-	-	-	PT4A	0	T	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-
E4	-	-	-	-	PT3B	0	-	-
E5	CFG0	0	-	-	CFG0	0	-	-
D4	CFG1	0	-	-	CFG1	0	-	-
D5	DONE	0	-	-	DONE	0	-	-
A1	GND	-	-	-	GND	-	-	-
A2	GND	-	-	-	GND	-	-	-
A21	GND	-	-	-	GND	-	-	-
A22	GND	-	-	-	GND	-	-	-
AA1	GND	-	-	-	GND	-	-	-
AA22	GND	-	-	-	GND	-	-	-
AB1	GND	-	-	-	GND	-	-	-
AB2	GND	-	-	-	GND	-	-	-
AB21	GND	-	-	-	GND	-	-	-
AB22	GND	-	-	-	GND	-	-	-
B1	GND	-	-	-	GND	-	-	-
B22	GND	-	-	-	GND	-	-	-
H14	GND	-	-	-	GND	-	-	-
H9	GND	-	-	-	GND	-	-	-
J10	GND	-	-	-	GND	-	-	-
J11	GND	-	-	-	GND	-	-	-
J12	GND	-	-	-	GND	-	-	-
J13	GND	-	-	-	GND	-	-	-
J14	GND	-	-	-	GND	-	-	-

Industrial (Cont.)

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP15E-3F484I	300	1.2V	-3	fpBGA	484	IND	15.5K
LFXP15E-4F484I	300	1.2V	-4	fpBGA	484	IND	15.5K
LFXP15E-3F388I	268	1.2V	-3	fpBGA	388	IND	15.5K
LFXP15E-4F388I	268	1.2V	-4	fpBGA	388	IND	15.5K
LFXP15E-3F256I	188	1.2V	-3	fpBGA	256	IND	15.5K
LFXP15E-4F256I	188	1.2V	-4	fpBGA	256	IND	15.5K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP20E-3F484I	340	1.2V	-3	fpBGA	484	IND	19.7K
LFXP20E-4F484I	340	1.2V	-4	fpBGA	484	IND	19.7K
LFXP20E-3F388I	268	1.2V	-3	fpBGA	388	IND	19.7K
LFXP20E-4F388I	268	1.2V	-4	fpBGA	388	IND	19.7K
LFXP20E-3F256I	188	1.2V	-3	fpBGA	256	IND	19.7K
LFXP20E-4F256I	188	1.2V	-4	fpBGA	256	IND	19.7K

Industrial (Cont.)

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP10C-3FN388I	244	1.8/2.5/3.3V	-3	fpBGA	388	IND	9.7K
LFXP10C-4FN388I	244	1.8/2.5/3.3V	-4	fpBGA	388	IND	9.7K
LFXP10C-3FN256I	188	1.8/2.5/3.3V	-3	fpBGA	256	IND	9.7K
LFXP10C-4FN256I	188	1.8/2.5/3.3V	-4	fpBGA	256	IND	9.7K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP15C-3FN484I	300	1.8/2.5/3.3V	-3	fpBGA	484	IND	15.5K
LFXP15C-4FN484I	300	1.8/2.5/3.3V	-4	fpBGA	484	IND	15.5K
LFXP15C-3FN388I	268	1.8/2.5/3.3V	-3	fpBGA	388	IND	15.5K
LFXP15C-4FN388I	268	1.8/2.5/3.3V	-4	fpBGA	388	IND	15.5K
LFXP15C-3FN256I	188	1.8/2.5/3.3V	-3	fpBGA	256	IND	15.5K
LFXP15C-4FN256I	188	1.8/2.5/3.3V	-4	fpBGA	256	IND	15.5K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP20C-3FN484I	340	1.8/2.5/3.3V	-3	fpBGA	484	IND	19.7K
LFXP20C-4FN484I	340	1.8/2.5/3.3V	-4	fpBGA	484	IND	19.7K
LFXP20C-3FN388I	268	1.8/2.5/3.3V	-3	fpBGA	388	IND	19.7K
LFXP20C-4FN388I	268	1.8/2.5/3.3V	-4	fpBGA	388	IND	19.7K
LFXP20C-3FN256I	188	1.8/2.5/3.3V	-3	fpBGA	256	IND	19.7K
LFXP20C-4FN256I	188	1.8/2.5/3.3V	-4	fpBGA	256	IND	19.7K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP3E-3QN208I	136	1.2V	-3	PQFP	208	IND	3.1K
LFXP3E-4QN208I	136	1.2V	-4	PQFP	208	IND	3.1K
LFXP3E-3TN144I	100	1.2V	-3	TQFP	144	IND	3.1K
LFXP3E-4TN144I	100	1.2V	-4	TQFP	144	IND	3.1K
LFXP3E-3TN100I	62	1.2V	-3	TQFP	100	IND	3.1K
LFXP3E-4TN100I	62	1.2V	-4	TQFP	100	IND	3.1K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP6E-3FN256I	188	1.2V	-3	fpBGA	256	IND	5.8K
LFXP6E-4FN256I	188	1.2V	-4	fpBGA	256	IND	5.8K
LFXP6E-3QN208I	142	1.2V	-3	PQFP	208	IND	5.8K
LFXP6E-4QN208I	142	1.2V	-4	PQFP	208	IND	5.8K
LFXP6E-3TN144I	100	1.2V	-3	TQFP	144	IND	5.8K
LFXP6E-4TN144I	100	1.2V	-4	TQFP	144	IND	5.8K

LatticeXP Family Data Sheet
Supplemental Information

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For Further Information

A variety of technical notes for the LatticeXP family are available on the Lattice website at www.latticesemi.com.

- LatticeECP/EC and LatticeXP sysIO Usage Guide (TN1056)
- Lattice ispTRACY Usage Guide (TN1054)
- LatticeECP/EC and LatticeXP sysCLOCK PLL Design and Usage Guide (TN1049)
- Memory Usage Guide for LatticeECP/EC and LatticeXP Devices (TN1051)
- LatticeECP/EC and XP DDR Usage Guide (TN1050)
- Power Estimation and Management for LatticeECP/EC and LatticeXP Devices (TN1052)
- LatticeXP sysCONFIG Usage Guide (TN1082)

For further information on interface standards refer to the following web sites:

- JEDEC Standards (LVTTL, LVCMOS, SSTL, HSTL): www.jedec.org
- PCI: www.pcisig.com